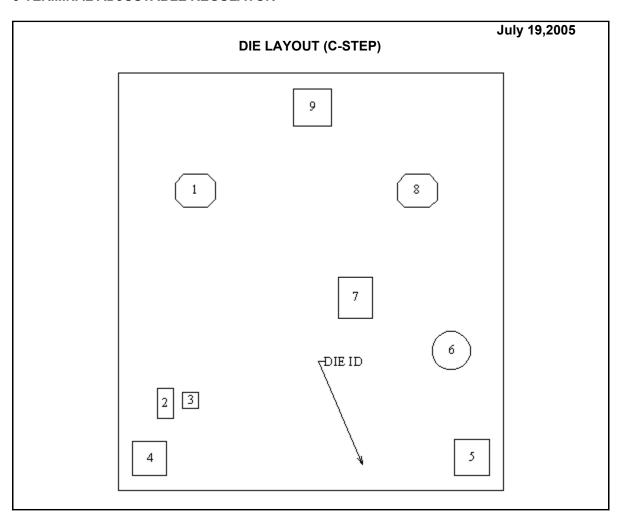


# LM117H MDS MCD2090A 3-TERMINAL ADJUSTABLE REGULATOR



## **DIE/WAFER CHARACTERISTICS**

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Fabrication Attributes		General Die Information							
Physical Die Identification	117C	Bond Pad Opening Size (min)	229µm x 188µm						
Die Step	С	Bond Pad Metalization	ALUMINUM						
Phys	Physical Attributes		VOM NITRIDE						
Wafer Diameter	150mm	Back Side Metal	Gold						
Die Size (Drawn)	2362μm x 2184μm 93.0mils x 86.0mils	Back Side Connection	OUTPUT						
Thickness	254μm Nominal		-						
Min Pitch	146µm Nominal								

Special Assembly Requirements:	
Note: Actual die size is rounded to the nearest micron.	



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	Die Bond Pad	Coordinate	Locations (C	-Step)		
(Referenced	to die center, coordi	nates in µm) <mark>N</mark>	C = No Connec	tion, N.U.	= Not	Used
SIGNAL	PAD#	X/Y COO	PAD SIZE			
NAME	NUMBER	X	Υ	Х		<u> Y</u>
OUTPUT	1	-655	516	229	х	188
NC	2	-827	-690	89	X	170
NC	3	-681	-673	91	X	91
OUTPUT	4	-914	-1001	193	Χ	198
ADJ	5	913	-997	196	Χ	206
NC	6	800	-391	208	X	208
INPUT	7	254	-91	193	Χ	234
OUTPUT	8	603	514	226	Χ	185
INPUT	9	10	987	213	Χ	211



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